

IN THE CLAIMS

Before claim 1, please add the following paragraph:

“WHAT IS CLAIMED IS:”

Please amend the claims as follows:

1. (Previously Presented) A component mounting apparatus for picking up electronic components supplied from a component supply and mounting the electronic components on a printed circuit board, the component mounting apparatus comprising:
 - a mounting head having a plurality of suction nozzles;
 - means for storing information on a predetermined sequence that such electronic components are supplied to the mounting head, the information comprising electronic component height and position information; and
 - means for controlling a position of the suction nozzles, the mounting head and a printed circuit board based on the information stored in the means for storing so that electronic components provided in the predetermined sequence are mounted in ascending order of height on a printed circuit board.
2. (Previously Presented) A component mounting apparatus for mounting components in ascending order of height, comprising:
 - a component supply section for supplying electronic components in a predetermined sequence;
 - a mounting head having suction nozzles for picking up the electronic components

from said component supply section and mounting the electronic components on a printed circuit board;

a data section for storing information on the predetermined sequence, the information comprising electronic component height and position information;

a component mounting section for positioning said plurality of suction, the mounting head and a printed circuit board based upon the height and component information stored in the data section; and

a control section connected to the data section for controlling said suction nozzles based upon the predetermined sequence so that the electronic components are mounted in ascending order of height based on the information previously stored in said data section.

3. (Previously Presented) A component mounting apparatus, for mounting components in ascending order of height, comprising:

a component supply section that supplies electronic components in a predetermined sequence;

a mounting head having a plurality of suction nozzles placed in a circular pattern for picking up the electronic components from said component supply section and for mounting the electronic components on a printed circuit board;

a data section for storing information on the predetermined sequence, the information comprising electronic component height and position information;

a component mounting section controlling the positioning of said suction nozzles, the mounting head and a printed circuit board; and

a control section connected to the data section and the component mounting section, the control section for providing control signals to said component mounting section for controlling vertical movements of said suction nozzles, intermittent rotations of the mounting head and horizontal movements of the component mounting section to mount such electronic components supplied in the predetermined sequence in ascending order of height based on the information supplied from said data section.

4. (Previously Presented) A component mounting apparatus for mounting components in ascending order of height, comprising:

a component supply section for supplying electronic components in a predetermined sequence;

a mounting head having at least one suction nozzles nozzle for picking up the electronic components from said component supply section and mounting the electronic components on a printed circuit board;

a data section for storing information on the predetermined sequence, the information comprising electronic component height and position information;

a component mounting section controlling the position of said at least one suction nozzle, the mounting head and a printed circuit board; and

a control section connected to the data section and the mounting section for providing control signals to said mounting section for controlling vertical movements of said suction nozzles and horizontal movements of the mounting head wherein the at least one suction nozzle and the mounting head are driven and controlled so that the components supplied in the

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predetermined sequence are mounted in ascending order of height based on the information supplied from said data section.

5. (Canceled).

6. (Canceled).

7. (Canceled).

8. (Canceled).

9. (Canceled).

10. (Canceled).

11. (Previously Presented) A component mounting apparatus for mounting components in ascending order of height, comprising:

a control section for deciding an order of mounting components supplied in a predetermined sequence based on previously stored information of mounting positions and heights of such components to mount the components in ascending order of height; and

a mounting head having suction nozzles for picking up components from a component supply section and mounting the components on a printed circuit board.

12. (Previously Presented) The component mounting apparatus of claim 11, further comprising:

a classifier for classifying into at least one group adjoining components spaced apart from each other at a distance shorter than a predetermined value, wherein said control section is for determining an order of mounting components of each said group.

13. (Previously Presented) The component mounting apparatus according to claim 11, further comprising a data section containing the information relating to mounting positions and heights of the components to be mounted.

14. (Previously Presented) The component mounting apparatus according to claim 12, further comprising a data section containing the information relating to mounting positions and heights of components to be mounted.

15. (Canceled).